

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

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Title: IC PACKAGE/THERMAL-SOLUTION RETENTION MECHANISM WITH SPRING EFFECT

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IN THE SPECIFICATION

Please amend the specification as follows:

Please amend the paragraph beginning at page 3, line 20 as follows:

Figure 2 shows a top view of one embodiment of a pressure plate 200. In one embodiment, the pressure plate 200 is a dish-shaped elastically deformable plate that has an apex (also referred to as a summit) 202 and a periphery 204. The pressure plate 200 may be deformed by applying a force 206 at the periphery 204, resulting in a force generally directed towards the apex 202. The force 206 is preferentially directed towards the apex 202 to avoid warping the circuit board 104.